

TFT SPECIFICATION

Part Number	USMP-T101-102060NAS-A0
Size	10.1"
Resolution	1024 x 600
Brightness	500 cd/m ²
Contrast	500:1
Viewing Angle	80/80/80/80
Operating Temp.	-30 ~ 85°C

FOR ADDITIONAL INFORMATION PLEASE CONTACT:

engineering@usmicroproducts.com

Issue Date	Approved by (customer use)	Checked by	Prepared by

PROPRIETARY NOTE: THIS SPECIFICATION IS THE PROPERTY OF US MICRO PRODUCTS AND SHALL NOT BE REPRODUCED OR COPIED WITHOUT THE WRITTEN PERMISSION OF US MICRO PRODUCTS AND MUST BE RETURNED TO US MICRO PRODUCTS UPON ITS REQUEST.

(800) 741-7755 www.usmicroproducts.com



History of Version

Date	Ver.	Edi.	Description	Page	Design by
12/20/2013	01	001	New Sample.	-	Ackey
01/20/2015	01	002	Add Label.	Appendix	Ackey
<u> </u>				Tota	al: 24 Page

Total: 24 Page



Contents

1. SPECIFICATIONS

- 1.1 Features
- **1.2 Mechanical Specifications**
- 1.3 Absolute Maximum Ratings
- **1.4 DC Electrical Characteristics**
- **1.5 Optical Characteristics**
- 1.6 Backlight Characteristics

2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- 3.2 Inspection Specification

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

Appendix : LCM Drawing

LCM Packaging Specifications



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	1024* (R、G、B) * 600 Dots
LCD Type	Normally white
Screen size(inch)	10.1(Diagonal)
Surface treatment	Anti-glare, Hard-Coating(3H)
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	LVDS

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	244.0(W) * 143.0 (L) * 12.4 (H)	mm

LCD panel

Item	Standard Value	Unit
Active Area	222.72 (W) * 125.28 (L)	mm

Note : For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Min.	Max.	Unit	
Supply Voltage	V	-0.3	3.6	V	Logic power supply voltage
Supply Voltage	V _{IN}	-0.3	24	V	LED Driver Vin
Power Supply Fuse Current Setting	I _{FUSE}	-	1.5	A	Vin from 10%~90%,rise time 500us
Input Signal	V_{S}	-	3.6	V	LVDS signals
PWM Voltage	V_{PWM}	0.8	5.0	V	PWM Dimming Voltage
Operating Temperature	TOP	-30	85	°C	
Operating Humidity	HOP	10	85	%RH	
Storage Temperature	TST	-30	85	°C	(1)
Storage Humidity	HST	10	85	%RH	

Note:

(1) The storage /operating temperature. Maximum Wet-Bulb should be 39 degree C. There is no condensation on the panel surface.



1.4 DC Electrical Characteristics

System Power Supply

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Input Power Supply Voltage	V _{IN}	3.0	3.3	3.6	V	
Input Power Supply Current	I _{VIN}	-	-	191	mA	Black pattern 60Hz
Input Inrush Current	I _{RUSH}	-	-	1.5	А	0.5ms rise time(10%~90%)
Input Power Voltage Ripple	V _{RPL}	-	-	200	mV	V _{P-P}
REV	VH	2.0	3.3	5.0	V	-
	VL	_	-	0.8	V	-

LED Power Supply

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Input Power Supply Voltage	V _{LED-IN}	8	12	16	V	
Input Power Supply Current	I _{IN}	-	-	546	mA	
EN/PWM	VH	2.0	3.3	5.0	V	
	VL	-	-	0.8	V	

LVDS Signals

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Differential Input High Threshold	V _{th}	-	-	+100	mV	V _{cm} =+1.2v
Differential Input High Threshold	V _{tl}	-100	-	-	mV	V _{cm} =+1.2v
Magnitude Differential Input Voltage	[V _{id}]	200	-	600	mV	
Common Mode Voltage	V _{cm}	1.0	1.2	1.4	V	V _{th} - V _{tl} = 200mV
Common Mode Voltage Offset	V _{cm}	-50	-	+50	mV	$V_{th} - V_{tl} = 200 \text{mV}$



1.5 Optical Characteristics

TFT LCD Panel

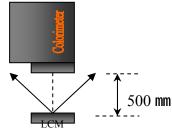
VDD=3.3V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	-
Response tin	ne	Tr + Tf	Ta = 25°C θX, θY = 0°	-	16	20	ms	Note2
	Тор	θY+		70	80	-		
	Bottom	θY-	CD > 10	70	80	-	Dea	Noto 4
Viewing angle	Left	θХ-	CR ≥ 10	70	80	-	Deg.	Note4
	Right	θX+		70	80	-		
Contrast rati	0	CR		400	500	-	-	Note3
	\//bito	Х	Ta = 25°C θX , θY = 0°	0.255	0.305	0.355		
	White	Y		0.275	0.325	0.375		
	Red	Х		0.529	0.579	0.629		
Color of CIE Coordinate		Y		0.294	0.344	0.394		Note1
(With B/L)	Croon	Х		0.276	0.326	0.376		NOLET
(((((((((((((((((((((((((((((((((((((((Green	Y		0.541	0.591	0.641		
	Blue	Х		0.109	0.159	0.209		
	Diue	Y		0.081	0.131	0.181		
Average Brightness Pattern=white display		IV		400	500	-	cd/m ²	Note1
Uniformity		В	-	75	-	-	%	Note1

Note1:

- 1 : B=B(min) / B(max) × 100%
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25 ±5 / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: 500 \pm 50 $\,$ mm $\,$, (0= 0^{\circ}) $\,$
 - c : Equipment: TOPCON BM-7 fast , (field 1°) , after 10 minutes operation.
 - d : The uncertainty of the C.I.E coordinate measurement ± 0.01 , Average Brightness $\pm 4\%$





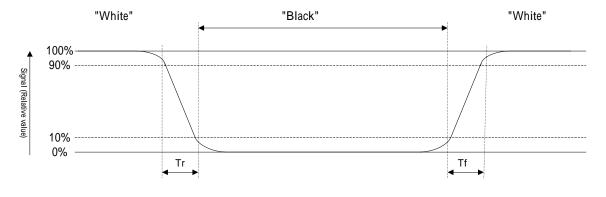
Colorimeter=BM-7 fast

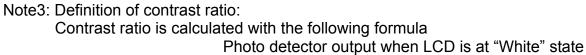


Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:

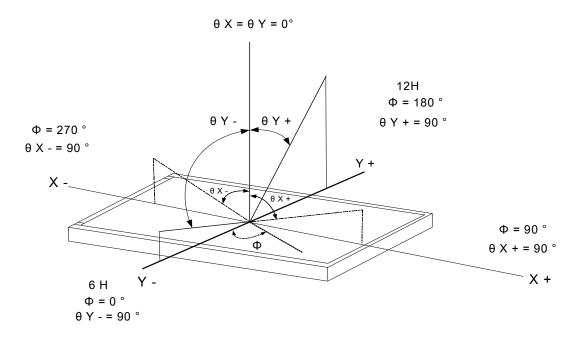




Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle: Refer to figure as below:





1.6 Backlight Characteristics

Ite	Item		Item		MIN	TYP	MAX	CONDITION
VIN_	LED	V	8	12	16	DUTY=100%		
VVIN	I_LED	mA	-	-	543	-		
F	МІС	HZ	100	-	1K	-		
DU	JTY	%	5	-	100	-		
CTRL	VIH	V	2	3.3	5	-		
CIRL	VIL	V	0	-	0.8	-		
Vo	DUT	V	-	22.4	-	-		
I _C	DUT	mA	-	160	-	-		
L	-T	Hours	50,000	-	-	LED Life Time		

Note : The LED life time define as the estimated time to 50% degradation of initial luminous.

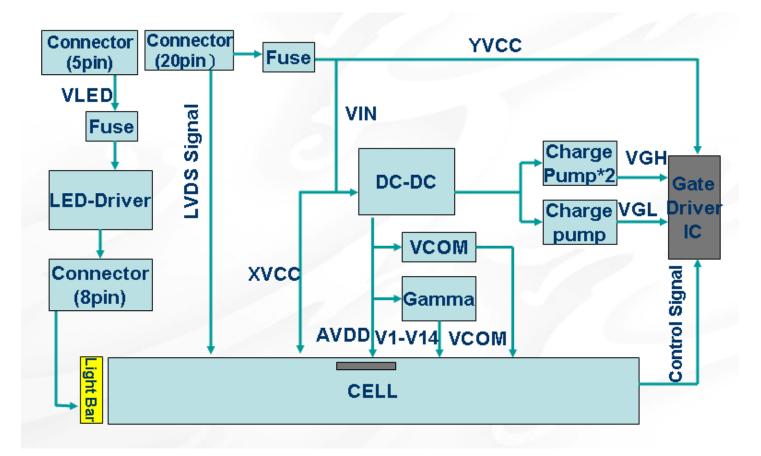


2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

- * See Appendix
- 2.1.2 Block Diagram





2.2 Interface Pin Description(CN1)

Pin No.	Symbol	Description	
1	VDD	Power Supply.3.3V (typical)	-
2	VDD	Power Supply.3.3V (typical)	-
3	VSS	Ground.	-
4	REV	Reverse Scan selection.	-
5	Rin 1-	-LVDS differential data input	-
6	Rin 1+	+LVDS differential data input	-
7	VSS	Ground.	-
8	Rin 2-	-LVDS differential data input.	-
9	Rin 2+	+LVDS differential data input.	-
10	VSS	Ground.	-
11	Rin 3-	-LVDS differential data input.	-
12	Rin 3+	+LVDS differential data input.	-
13	VSS	Ground.	-
14	ClkIN-	-LVDS differential data input.	-
15	ClkIN+	+LVDS differential data input.	-
16	VSS	Ground.	-
17	NC	Not connection.	-
18	NC	Not connection.	-
19	VSS	Ground.	-
20	NC	Not connection.	High Active



B/L Pin Assignment(CN2)

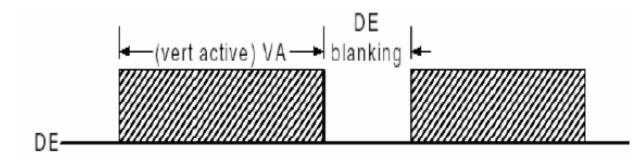
Pin No.	Symbol	Description	Remarks
1	VCC	Power Supply. 12V(typical).	-
2	GND	Ground.	-
3	EN	3.3V (typical)	-
4	PWM	3.3V (typical)	-
5	NC	Not Connection	-



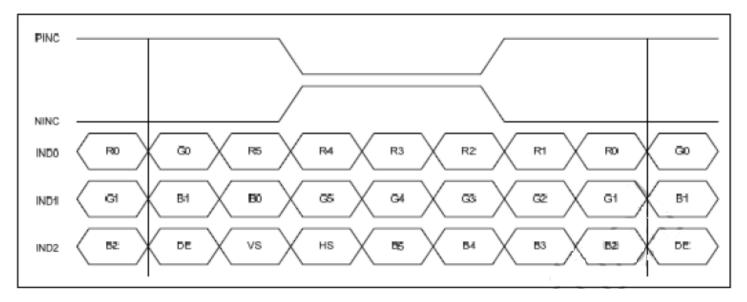
2.3 Timing Characteristics

Parameter	Symbol	Unit	Min.	Тур.	Max.
LVDS Clock Frequency <single></single>	f dck	MHz	45	51.2	57
H Total Time	T _{hp}	clocks	1,324	1,344	1,364
H Active Time	HA	clocks	1,024	1,024	1,024
H Blanking Time		clocks	300	320	340
∨ Total Time	T _{vp}	lines	625	635	645
V Active Time	VA	lines	600	600	600
∨ Blanking Time		lines	25	35	45
∨ Frequency	f _v	Hz	55	60	65

DE Synchronization



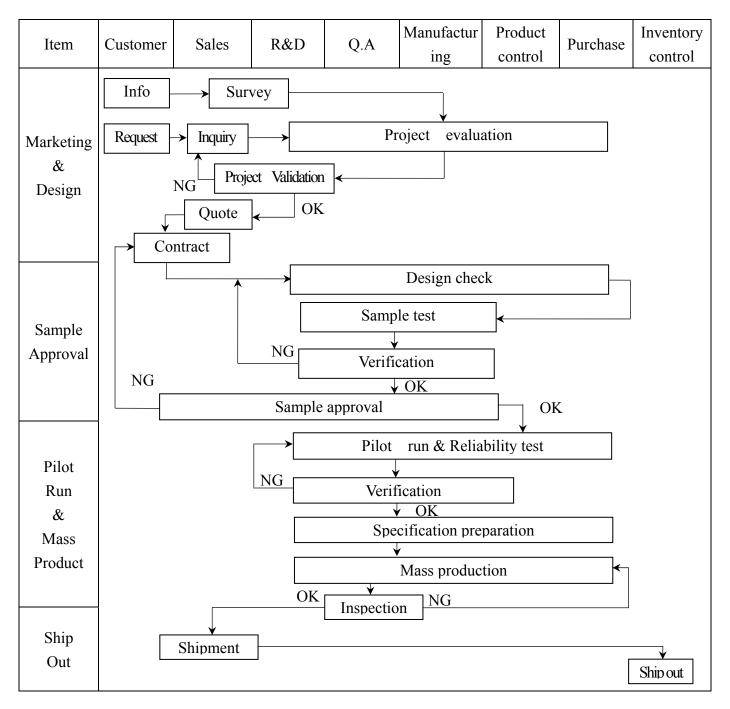
LVDS Data Mapping





3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart





Item	Customer	Sales	R&D	Q.A	Manufactu ring	Product control	Purchase	Inventory control
Sales Service	Info	Claim sis report	[Trackin	Failure an Corrective			
Q.A Activity	 ISO 9001 Equipment Standardi 		n		ocess improv Education An	1 1		



3.2. Inspection Specification

Scope : The document shall be applied to TFT-LCD Module for 3.5" ~10.1" (Ver.B01).

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level

Equipment : Gauge, MIL-STD, Tester, Sample

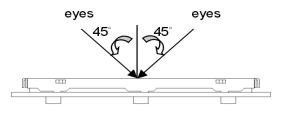
Defect Level : Major Defect AQL : 0.4 ; Minor Defect AQL : 1.5

OUT Going Defect Level : Sampling.

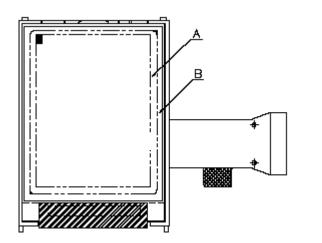
Standard of the product appearance test :

a. Manner of appearance test :

- (1). The test best be under 20W×2 fluorescent light , and distance of view must be at 30 cm.
- (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area : viewing area

B area : Outside of viewing area

(4). Standard of inspection : (Unit : mm)



Specification For TFT-LCD Module 3.5" ~10.1" :

NO	Item			Criteri	ion		Level
			part nun duction.	nber is inconsistent	with work order of		Major
01	Product condition	1.2 Mix	ed produ	ıct types.			Major
		1.3 Asso	3 Assembled in inverse direction.				
02	Quantity	2.1The	quantity	is inconsistent with	work order of producti	on.	Major
03	Outline dimension		duct din gram.	nension and structu	ire must conform to sti	ructure	Major
		4.1 Mis	sing line	character and icon.			Major
		4.2 No function or no display.				Major	
04	Electrical Testing	4.3 Display malfunction.				Major	
		4.4 LCD viewing angle defect.				Major	
		4.5 Cur	rent con	sumption exceeds p	roduct specifications.		Major
		[Item	Acceptance (Q'ty)		
				Bright Dot	4		
	Dot defect		Dot	Dark Dot	5		
			Defect	Joint Dot	3		
05	(Bright dot、 Dark dot)			Total	7		Minor
05	On -display	5.2 It is	defined	blue screen as dot defect if defe	ect area > 1/2 dot.	en and	
				e between two dot do that can be seer	efect 5 mm. n through 5% ND filte	er.	

(Ver.B01)



Specification For TFT-LCD Module 3.5" ~10.1" :

Speci	fication For TFT-L	CD Module 3.5	~10.1 :				(Ver.B0
NO	Item		Cri	iterion			Level
06	Black or white dot, scratch, contamination Round type $\xrightarrow{Y} X \xrightarrow{Y} Y$	6.1 Round type Dimensio 0.25 Total 6.2 Line type(N	n (diameter : Φ) Φ 0.25 $< \Phi$ 0.50 Φ > 0.50) Ac Aa Ignore 5 00	rea	(Q'ty) B area	Mino
	$\Phi = (x + y) / 2$ Line type	Length (L)	Width (W)	Accepta A area	ance (Q'ty) B area	
	$ \underset{L}{\overset{\bullet}{\to}} $	 L 10.0	W 0.03 < W	0.03	Ignore 4		
		L 5.0	0.05 < W	0.10	2 As roun	Ignore	
		 Total	W	> 0.10	type 5		
	Polarizer Bubble	Dimension ((diameter : Φ) Φ 0.25	Ac A an Ignore	rea	(Q'ty) B area	
07			$0.25 < \Phi = 0.50$			T	Mino
		0.50 <	Φ 0.80 Φ > 0.80	1		Ignore	
		Т	otal	5			



Specification For TFT-LCD Module 3.5" ~10.1":

(Ver.B01)

NO	Item		Criterion		Level
		Z: The th	ickness of crack	Y : The width of crack. W : terminal length a : LCD side length	
			al glass chip : ip on panel surface and cra	ack between panels:	
			Y Z	Y X X	
08	The crack of glass	SP	Y (OK)	ING J	Minor
			Seal width	Y	
		X	Y	Z	
		a	Crack can't enter viewing area	1/2 t	
		a	Crack can't exceed the half of SP width.	1/2 t < Z 2 t	



NO	Item		Criterion		Level		
		Symbols :X : The length of crackY : The width of crack.Z : The thickness of crackW : terminal lengtht : The thickness of glassa : LCD side length8.1.2 Corner crack : $X + Z = Z = Z = Z = Z = Z = Z = Z = Z = Z$					
		X	Y	Z			
		1/5 a	Crack can't enter viewing area	Z 1/2 t			
		1/5 a	Crack can't exceed the half of SP width.	1/2 t < Z 2 t			
08	The crack of glass	8.2 Protrusion over terminal :					
08		8.2.1 Chi	p on electrode pad :	X Y Z			
			X	ž Z			
		Front	t a 1	/2 W t			
		Back	a	W 1/2 t			

Specification For TFT-LCD Module 3.5" ~10.1" :



	Level
Symbols : X : The length of crack Y : The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length 8.2.2 Non-conductive portion : W Y Z Y Z X Y X Y Z X Y Z 1/3 a W X Y	Mino
A : The length of crack X : The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length 8.2.2 Non-conductive portion : V V V V X X X X X X X X	Π

TET I CD Madula 2 5" 10 4" .:**r**: .. _ -



Specification For TFT-LCD Module 3.5" ~10" :

Specif	ication For TFT-L	2CD Module 3.5"~10":	(Ver.B01)
NO	Item	Criterion	Level
		9.1 Backlight can't work normally.	Major
09	Backlight elements	9.2 Backlight doesn't light or color is wrong.	Major
		9.3 Illumination source flickers when lit.	Major
		10.1 Pin type, quantity, dimension must match type in structure diagram.	Major
		10.2 No short circuits in components on PCB or FPC .	Major
10		10.3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10	appearance	10.4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10.5 The folding and peeled off in polarizer are not acceptable.	Minor
		10.6 The PCB or FPC between B/L assembled distance(PCB or FPC) is 1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

(Ver.B01)

NO.	TEST ITEM	TEST CONDITION						
1	High Temperature Storage Test	Keep in +80 ±2 96 hrs Surrounding temperature, then st	Keep in +80 ±2 96 hrs Surrounding temperature, then storage at normal condition 4hrs.					
2	Low Temperature Storage Test	Keep in -30 ±2 96 hrs Surrounding temperature, then st	Keep in -30 ±2 96 hrs Surrounding temperature, then storage at normal condition 4hrs.					
3	High Temperature / High Humidity Storage Test	1	Surrounding temperature, then storage at normal condition 4hrs.					
4	Temperature Cycling Storage Test	-30 +25 +80 +25 (30mins) (5mins) (30mins) (5mins) 10 Cycle Surrounding temperature, then storage at normal condition 4hrs.						
5	ESD Test	 Energy Storage Capacitance(C Discharge Resistance(Rd) : 336 Discharge, mode of operation 	Air Discharge:Contact Discharge:Apply 2 KV with 5 timesApply 250 V with 5 timesDischarge for each polarity +/-discharge for each polarity +/-1. Temperature ambiance : 15352. Humidity relative : 30% 60%3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%4. Discharge Resistance(Rd) : 330 ±10%5. Discharge, mode of operation :Single Discharge (time between successive discharges at least 1 sec)					
6	Vibration Test (Packaged)	 Sine wave 10 55 Hz frequent The amplitude of vibration :1. Each direction (X, Y, Z) du 	5 mm					
7	Drop Test (Packaged)	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454	Drop Height (cm) 122 76 61 46					



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

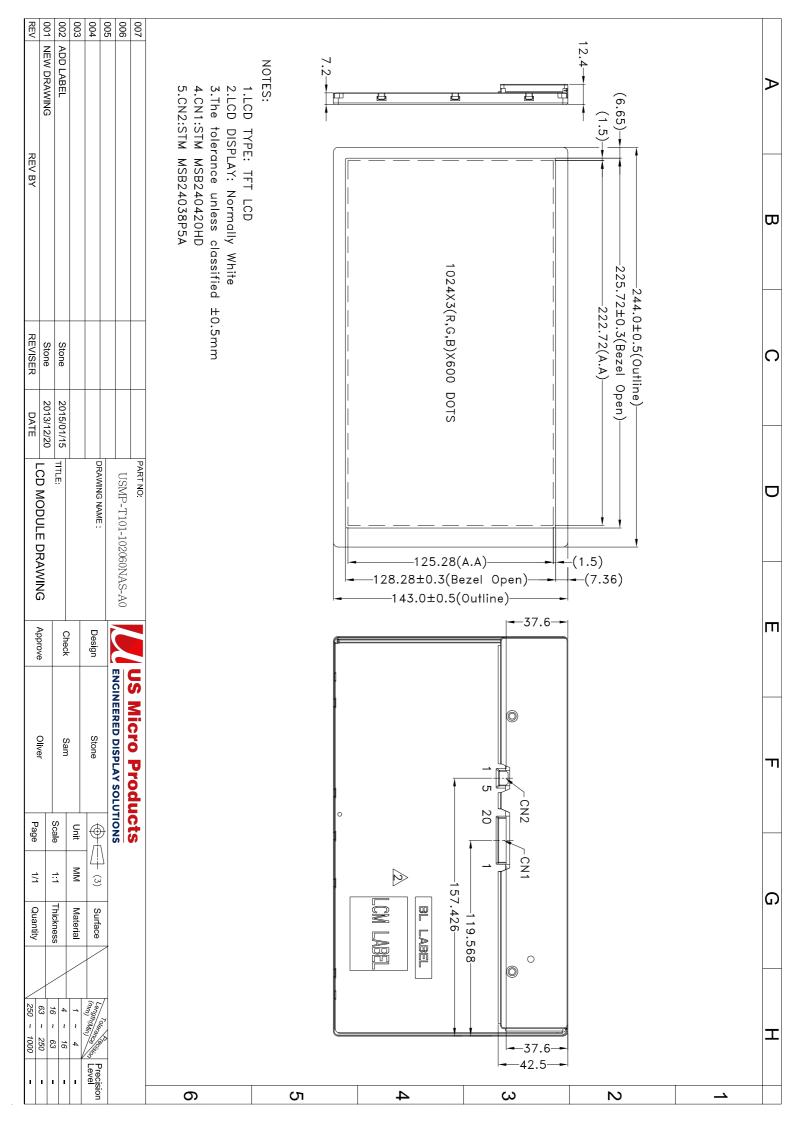
5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Ver	r.002 US Micro Products ENGINEERED DISPLAY SOLUTIONS	I.CM作	回裝規格書	F	Approve	Check	Contact
Doc	cuments NO.		jing Specification	าร	Oliver	Sam	Stone
1 /							
	回裝材料規格表 (Packaging Materia		Dimensions (mm)	1Dag	Waialat	Operatity	Tatal Waia
No.		Model	Dimensions (mm)		Weight	Quantity 20	Total Weig
$\frac{1}{2}$	成品 (LCM) 輕素代(1) A stistatis Dag		244.0 X 143.0 240 X 300		41		8.2
<u>2</u> 3	靜電袋(1)Antistatic Bag 上蓋(2)EPE(Cover)		520 X 315 X 65		008 108	20	0.16
3 4	下座(3)EPE(Bottom)		520 X 315 X 05		85	1	0.108
5	外紙箱(4)Carton		527 X 325 X 360		092	1	1.092
6			521 A 525 A 500	1.	.072	-	1.072
	亞箱數量規格表 (Packaging Specificatio otal LCM quantity in carton : quantity page otal to the		x no of EPE	1	=	20	
			/				
	(2)上蓋						
	EPE(Cover)						
	Ϋ́						
	V						
	(1)靜電袋+LCM Antistatic Bag+LCM				₩	_	
	$\overline{\mathbb{V}}$				\bigcirc		
				$\langle $		\gg	1
					\		
	(3)下座		4	\searrow			J
	EPE(Bottom)		(4)外紙箱/		\searrow		
			Carton			\downarrow	
		特記事	項 (REMARK)	1			